

IN THE CLAIMS:

Claims 1-6 have been amended herein. All of the pending claims 1 through 6 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Currently Amended) A method of forming a semiconductor device assembly, said method comprising:
providing a substrate having an upper surface and a lower surface;
depositing a layer of copper on one surface of the upper surface and the lower surface of the substrate;
patterning the layer of copper ~~on~~ on the one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon;
depositing at least one layer of metal on at least a portion of the layer of copper; and
connecting one end of a conductor lead of a TAB tape to the at least one layer of metal.

2. (Currently Amended) The method of claim 1, further comprising:
connecting one end ~~of~~ of the conductor lead of a the TAB tape to the at least one layer of ~~gold~~ metal using a wire bond.

3. (Currently Amended) A method of forming a semiconductor device assembly, said method comprising:
providing a substrate having an upper surface and a lower surface;
depositing a layer of copper ~~on~~ on the one surface of the upper surface and the lower surface of the substrate;
patterning the layer of copper on one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon;
depositing at least one layer of gold metal on at least a portion of the layer of copper; and
connecting one end of a conductor lead of a TAB tape to the at least one layer of gold metal.

4. (Currently Amended) A method of forming a semiconductor device assembly having a substrate having an upper surface and a lower surface, said method comprising: depositing a layer of copper on one surface of the upper surface and the lower surface of the substrate; patterning the layer of copper ~~on~~ on the one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon; depositing at least one layer of metal on at least a portion of the layer of copper; and connecting one end of a conductor lead of a TAB tape to the at least one layer of metal.

5. (Currently Amended) The method of claim 4, further comprising: connecting one end ~~of~~ of the conductor lead of ~~a~~ a the TAB tape to the at least one layer of ~~gold~~ metal using a wire bond.

6. (Currently Amended) A method of forming a semiconductor device assembly having a substrate having an upper surface and a lower surface, said method comprising: depositing a layer of copper on one surface of the upper surface and the lower surface of the substrate; patterning the layer of copper ~~on~~ on the one surface of the upper surface and the lower surface of the substrate to form at least one bond pad thereon; depositing at least one layer of gold metal on at least a portion of the layer of copper; and connecting one end of a conductor lead of a TAB tape to the at least one layer of gold metal.

IN THE DRAWINGS:

The attached sheet of drawings includes changes to FIGS. 4C and 4D. This sheet, which includes FIGS. 4C and 4D, replaces the original sheet including FIGS. 4C and 4D.